

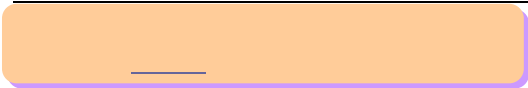


有铅

Sn63/Pb37 Sn60/Pb40, Sn55Pb45, SnPbBi

- 1 0.2mm
- 2 12
- 3
- 4
- 5
- 6 --- PCB
- 7 ICT
- 8 Paste in hole

	ROL1	J-STD-004
卤素	0.15wt%	
(SIR)	1×10^{13}	25mil
	1×10^{12}	40 90%RH 96Hrs
	1×10^5	
		IPC-TM-650
		IPC-TM-650
		In house
	85~91wt% ± 0.5	
	9~15wt% ± 0.5	
	220 ± 30 Pa.s Malcolm (10rpm, 2)	T5, 89% metal for printing
	160 Pa.s $\pm 10\%$ Malcolm (10rpm, 2)	T4, 87% metal for syringe
	0.55 ± 0.05	In house
	90%	Copper plate (Sn63, 90% metal)
		J-STD-005
		In house
Vs	48gF 0	IPC-TM-650 $\pm 5\%$
	56gF 2	
	68gF 4	
	44gF 8	
	12	In house
		0~10



1

T3 mesh -325/+500 25~45μ m

Fine pitch

2

1) “ ”

0~10

200

4

2)

3

1 ;

3



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0.4mm

0.12mm



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80%

	60 ~ 90HS
	45 ⁰ ~ 60 ⁰
	2 ~ 4 × 10 ⁵ pa
	20 ~ 40mm/sec 15 ~ 20mm/sec 50 ~ 100mm/sec
	25 ± 3 40 ~ 70%



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PCB

PCB

A5

200g

B5

300g

A4

400g

4

4

5

6

此有铅



500g

PE

20

35



0 ~10

•

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0

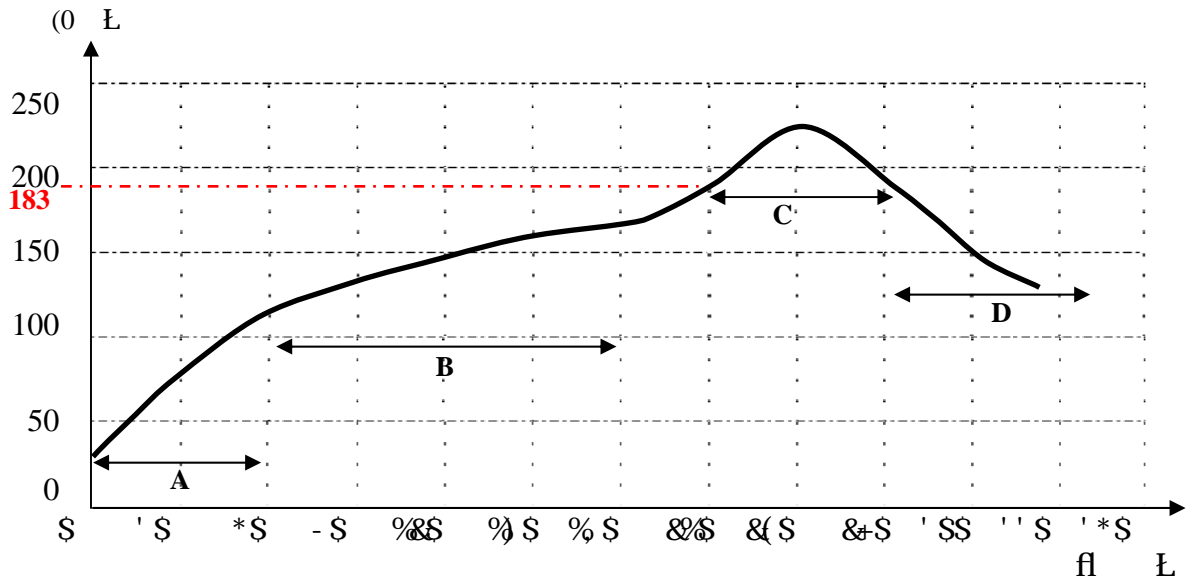
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MSDS

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Sn63/Pb37 Sn60/Pb40, Sn55Pb45, SnPbBi



A. 25~33%

* 1.0~3.0 /
*

B. 33~50%

* 130~170 60~120 2 /
PCB

C.

* 210~240 183 40~90 Important 200 20~50
*
*

D.

* 4 75
*
*

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-
-